

## PATENT ASSIGNMENT COVER SHEET

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
JONG HYEON CHAE	12/26/2014
JONG MIN JANG	12/26/2014
WON YOUNG ROH	12/26/2014
DAE WOONG SUH	12/26/2014
MIN WOO KANG	12/26/2014
JOON SUB LEE	12/26/2014
HYUN A. KIM	12/26/2014
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<b>Internal Address:</b>	DANWON-GU, GYEONGGI-DO
<b>City:</b>	ANSAN-SI
<b>State/Country:</b>	KOREA, REPUBLIC OF
<b>Postal Code:</b>	15429
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
Application Number:	16889525
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<b>ATTORNEY DOCKET NUMBER:</b>	114896-8028.US03
<b>NAME OF SUBMITTER:</b>	MICHAIAH COPP
<b>SIGNATURE:</b>	/Michaiah Copp/

<b>DATE SIGNED:</b>	06/11/2020
	This document serves as an Oath/Declaration (37 CFR 1.63).
<b>Total Attachments: 5</b> source=Executed_Declaration_Assignment_114896-8028US03#page1.tif source=Executed_Declaration_Assignment_114896-8028US03#page2.tif source=Executed_Declaration_Assignment_114896-8028US03#page3.tif source=Executed_Declaration_Assignment_114896-8028US03#page4.tif source=Executed_Declaration_Assignment_114896-8028US03#page5.tif	

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Patent Application of:  
Jong Hyeon Chae et al.

Application No.: Not Yet Assigned

Conf. No.: Not Yet Assigned

Filed: Herewith

For: LIGHT EMITTING DIODE FOR SURFACE MOUNT  
TECHNOLOGY, METHOD OF MANUFACTURING THE  
SAME, AND METHOD OF MANUFACTURING LIGHT  
EMITTING DIODE MODULE

**DECLARATION AND ASSIGNMENT BY THE INVENTOR  
UNDER RULE 37 C.F.R. § 1.63 EFFECTIVE ON SEPTEMBER 16, 2012**

As a below named inventor, I hereby declare that:

I believe I am the sole original inventor or an original joint inventor of a claimed invention in a patent application entitled:

**LIGHT EMITTING DIODE FOR SURFACE MOUNT TECHNOLOGY,  
METHOD OF MANUFACTURING THE SAME, AND METHOD OF  
MANUFACTURING LIGHT EMITTING DIODE MODULE**

filed on December 29, 2014, and assigned U.S. Application Number 14/585,125, the specification of which is attached hereto and identified as Attorney Docket No. 114896-8028.US00. I authorize and request an attorney appointed in the above-identified U.S. application to hereafter insert above the filing date and application number of the above-identified U.S. patent application when known.

I believe the following persons are original joint inventors of the above-identified U.S. patent application:

Jong Hyeon Chae;

Jong Min Jang;

Won Young Roh;

Dae Woong Suh;

Min Woo Kang;

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Joon Sub Lee; and  
Hyun A. Kim.

I made, authorized to make, or will make or authorize to make the above-identified patent application at the U.S. Patent and Trademark Office.

I have reviewed and understand the contents of the above-identified patent application including the claims.

I am aware of the duty to disclose to the U.S. Patent and Trademark Office all information known to me to be material to patentability as defined in 37 CFR §1.56.

I hereby acknowledge that any willful false statement made in the above declaration is punishable under 18 USC §1001 by fine or imprisonment of not more than five (5) years, or both.

#### ASSIGNMENT

I hereby assign to Seoul Viosys Co., Ltd., a corporation, having a place of business at #1B-36, 65-16, Sandan-ro 163beon-gil, Danwon-gu, Ansan-si, Gyeonggi-do 425-851, Republic of Korea, and its successors and assigns (collectively "the Assignee"), the entire right, title and interest throughout the world in any and all inventions and improvements which are described in the above-identified application, and prior PCT Application No. PCT/KR2013/005254 of the same title, filed in the Republic of Korea Receiving Office on June 14, 2013, and prior Korean Patent Application No. 10-2012-0070129 filed in the Republic of Korea on June 28, 2012 from which the above-identified U.S. patent application claims priority and benefits.

This assignment includes the entire right, title and interest in the above-identified U.S., PCT and Korean patent applications, all legal equivalents thereof in any country, any and all United States, Patent Cooperation Treaty, Republic of Korea and other foreign patents, utility models, and design registrations granted for any of said inventions and improvements, including, but not limited to, all divisions, continuations, reissues, reexamination certificates, any and all certificates issued in any post-grant proceeding, and extensions of said applications and patents of the United States, Patent Cooperation Treaty and Republic of Korea, all other foreign patents, utility models, and design registrations, and the right to claim priority based on the filing dates of the above-identified U.S. and Republic of Korea patent applications under the International

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Convention for the Protection of Industrial Property, the Patent Cooperation Treaty, the European Patent Convention, and all other treaties of like purposes, and the right to seek relief and recover all damages, including, but not limited to, a reasonable royalty, by reason of infringement or any other violation of patent or patent application rights. I authorize the Assignee to apply in all countries in the name of the Assignee for patents, utility models, design registrations and like rights of exclusion and for inventors' certificates for said inventions and improvements.

In addition, I hereby confirm the sale, assignment, and transfer to the Assignee of the entire right, title and interest throughout the world in said inventions and improvements that occurred by operation of an employment agreement between me and the Assignee existing at the time said inventions and improvements were made. Should I have any remaining interest, I hereby sell, assign, and transfer any right, title and interest I may have in said inventions and improvements anywhere in the world to the Assignee.

The foregoing assignments, sale and transfer have been made for good and valuable consideration in accordance with the aforementioned employment agreement.

I hereby represent and covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into that would conflict with the assignment of said inventions and improvements to the Assignee.

I further covenant for myself and my respective heirs, legal representatives and assigns, to assist the Assignee in handling various procedures, tasks and documentation in connection with this assignment, including, but not limited to, providing to the Assignee promptly upon the request of the Assignee all pertinent facts and documents relating to said invention and improvements, and said patents, said legal equivalents or other legal instrument as may be known and accessible to me and testifying as to the same in any interference, litigation, or proceeding relating thereto, and promptly executing and delivering to the Assignee or its legal representative any and all papers, documents, instruments or affidavits in connection with obtaining, maintaining, issuing or enforcing said application, said inventions and improvements, and said patents, said equivalents and other legal instrument which may be necessary or desirable to carry out the purposes thereof.

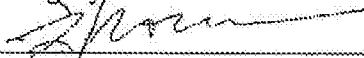
Inventors : Jong Hyeon Chae et al.  
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I hereby authorize and request the Commissioner of Patents and Trademarks to issue one or more patents in the United States for said inventions and improvements to Seoul Viosys Co., Ltd. as assignee of the entire interest, for the sole use and benefit of Assignee, its successors and assigns.


I am competent to execute the above declaration and assignment. I hereby have duly executed the declaration and assignment below with my name.

Full name of first inventor: Jong Hyeon Chae

Inventor's signature: 

Date: December 26, 2014

Full name of joint inventor: Jong Min Jang

Inventor's signature: 

Date: December 26, 2014

Full name of joint inventor: Won Young Roh

Inventor's signature: 

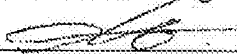
Date: December 26, 2014

Full name of joint inventor: Dae Woong Suh

Inventor's signature: 

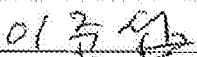
Date: December 26, 2014

Full name of joint inventor: Min Woo Kang

Inventor's signature: 

Date: December 26, 2014

Full name of joint inventor: Joon Sub Lee

Inventor's signature: 

Date: December 26, 2014

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Full name of joint inventor: Hyun A. Kim

Inventor's signature: 김현아

Date: December 26, 2014

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